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25-Ω OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SDFS100 – JANUARY 1996

- Eight Latches in a Single Package
- 3-State True Outputs With 25-Ω Sink Resistors
- Full Parallel Access for Loading
- Buffered Control Inputs
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB) Packages, and Plastic (N) DIPs

description

This 8-bit latch features 3-state outputs designed to sink up to 12 mA, and include 25-Ω sink resistors to reduce overshoot and undershoot.

The eight latches of the SN74F2373 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When the LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

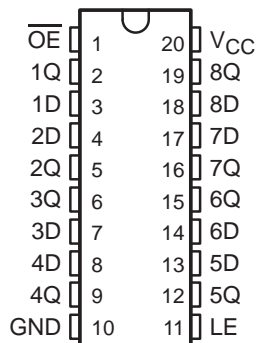
A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

\overline{OE} input does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN74F2373 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN74F2373 is characterized for operation from 0°C to 70°C.

DB, DW, OR N PACKAGE (TOP VIEW)



FUNCTION TABLE (each latch)

| INPUTS | | | OUTPUT |
|-----------------|----|---|--------|
| \overline{OE} | LE | D | Q |
| L | H | H | H |
| L | H | L | L |
| L | L | X | Q_0 |
| H | X | X | Z |



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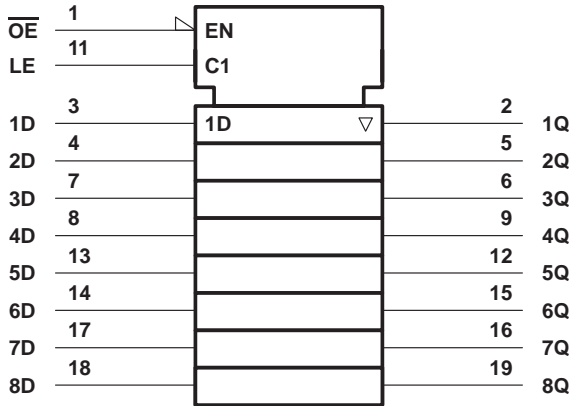
SN74F2373

25-Ω OCTAL TRANSPARENT D-TYPE LATCH

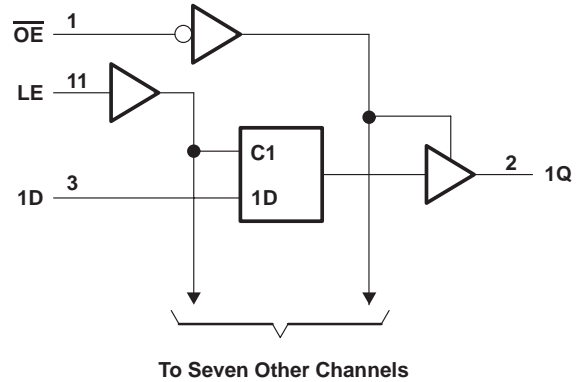
WITH 3-STATE OUTPUTS

SDFS100 – JANUARY 1996

logic symbol†

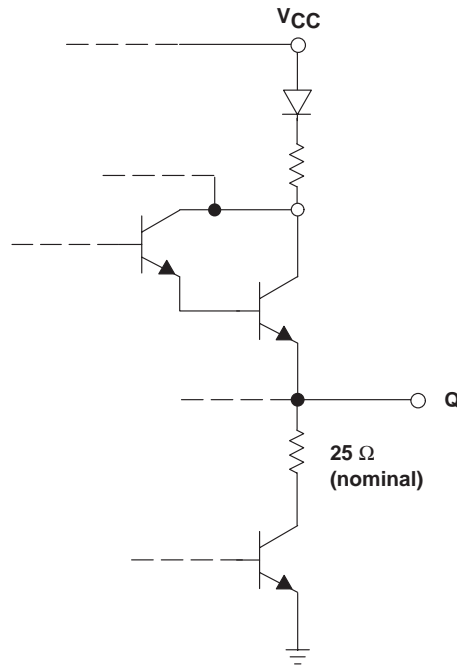


logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

schematic diagram



Typical Output Configuration

SN74F2373
25-Ω OCTAL TRANSPARENT D-TYPE LATCH
WITH 3-STATE OUTPUTS

SDFS100 – JANUARY 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|---|--------------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -1.2 V to 7 V |
| Input current range, I_I | -30 mA to 5 mA |
| Voltage range applied to any output in the disabled or power-off state, V_O | -0.5 V to 5.5 V |
| Voltage range applied to any output in the high state, V_O | -0.5 V to V_{CC} |
| Current into any output in the low state, I_O | 30 mA |
| Operating free-air temperature range, T_A | 0°C to 70°C |
| Storage temperature range, T_{stg} | -65°C to 150°C |

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded if the input current ratings are observed.

recommended operating conditions

| | MIN | NOM | MAX | UNIT |
|--------------------------------------|-----|-----|-----|------|
| V_{CC} Supply voltage | 4.5 | 5 | 5.5 | V |
| V_{IH} High-level input voltage | 2 | | | V |
| V_{IL} Low-level input voltage | | | 0.8 | V |
| I_{IK} Input clamp current | | | -18 | mA |
| I_{OH} High-level output current | | | -3 | mA |
| I_{OL} Low-level output current | | | 12 | mA |
| T_A Operating free-air temperature | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP‡ | MAX | UNIT |
|-------------|--|------------------|------|------|------|
| V_{IK} | $V_{CC} = 4.5$ V, $I_I = -18$ mA | | | -1.2 | V |
| V_{OH} | $V_{CC} = 4.5$ V | $I_{OH} = -1$ mA | 2.5 | 3.4 | V |
| | | $I_{OH} = -3$ mA | 2.4 | 3.3 | |
| | $V_{CC} = 4.75$ V, $I_{OH} = -1$ mA to -3 mA | 2.7 | | | |
| V_{OL} | $V_{CC} = 4.5$ V | $I_{OL} = 1$ mA | 0.2 | 0.5 | V |
| | | $I_{OL} = 12$ mA | 0.5 | 0.75 | |
| $I_{OZ(H)}$ | $V_{CC} = 5.5$ V, $V_O = 2.7$ V | | | 50 | μA |
| $I_{OZ(L)}$ | $V_{CC} = 5.5$ V, $V_O = 0.5$ V | | | -50 | μA |
| I_I | $V_{CC} = 5.5$ V, $V_I = 7$ V | | | 0.1 | mA |
| I_{IH} | $V_{CC} = 5.5$ V, $V_I = 2.7$ V | | | 20 | μA |
| I_{IL} | $V_{CC} = 5.5$ V, $V_I = 0.5$ V | | | -0.6 | mA |
| $I_{OS}§$ | $V_{CC} = 5.5$ V, $V_O = 0$ | -60 | | -150 | mA |
| $I_{CC(H)}$ | $V_{CC} = 5.5$ V, See Note 2, Condition A | | 38 | 55 | mA |
| $I_{CC(L)}$ | $V_{CC} = 5.5$ V, See Note 2, Condition B | | 46 | 66 | mA |
| $I_{CC(Z)}$ | $V_{CC} = 5.5$ V, See Note 2, Condition C | | 43 | 62 | mA |

‡ All typical values are at $V_{CC} = 5$ V, $T_A = 25$ °C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2:

I_{CC} is measured with the outputs open under the following conditions:

- A. \overline{OE} at ground (0) and all other inputs at 4.5 V.
- B. \overline{LE} at 4.5 V and all other inputs grounded.
- C. \overline{OE} at 4.5 V and all other inputs grounded.

SN74F2373

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

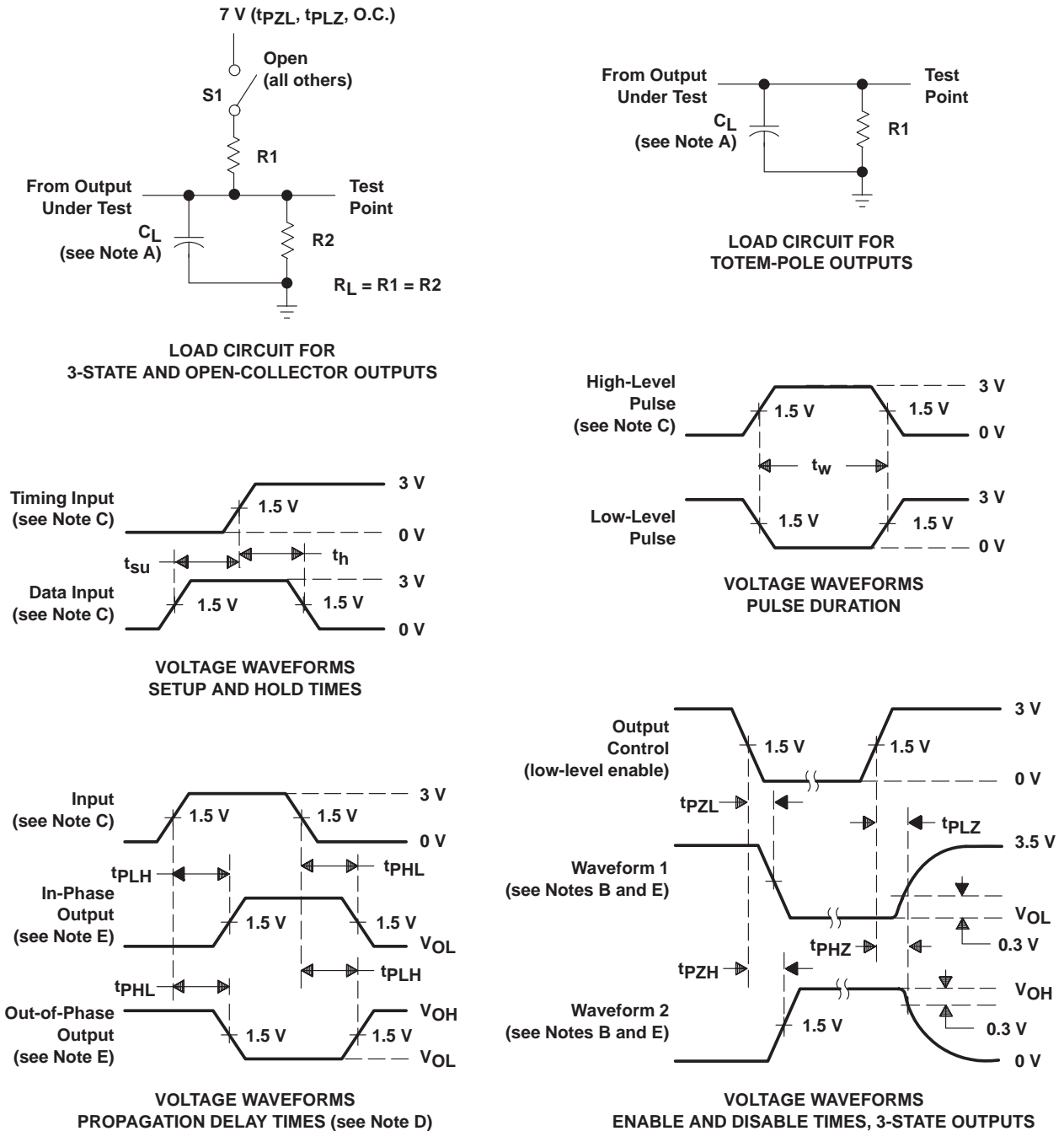
| | | V _{CC} = 5 V, T _A = 25°C | | MIN | MAX | UNIT |
|-----------------|-----------------------------|---|-----|-----|-----|------|
| | | MIN | MAX | | | |
| t _w | Pulse duration, LE high | 6 | | 6 | | ns |
| t _{su} | Setup time, data before LE↓ | 2 | | 2 | | ns |
| t _h | Hold time, data after LE↓ | 5 | | 6 | | ns |

switching characteristics (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 5 V, C _L = 50 PF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = 25°C | | | V _{CC} = 4.5 V TO 5.5 V, C _L = 50 PF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN TO MAX† | | UNIT |
|------------------|-----------------|----------------|--|-----|------|--|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | |
| t _{PLH} | D | Q | 2.2 | 4.4 | 7 | 2.1 | 9 | ns |
| t _{PHL} | | | 1.2 | 4.1 | 5.5 | 1.2 | 7 | |
| t _{PLH} | LE | Q | 4.2 | 7.3 | 11.5 | 4.2 | 13 | ns |
| t _{PHL} | | | 2.2 | 4.2 | 7 | 2.2 | 8 | |
| t _{PZH} | \overline{OE} | Q | 1.2 | 4.1 | 11 | 1.2 | 12 | ns |
| t _{PZL} | | | 1.2 | 6 | 8.3 | 1.2 | 9.5 | |
| t _{PHZ} | \overline{OE} | Q | 1.2 | 4.2 | 6.5 | 1.2 | 7.5 | ns |
| t _{PLZ} | | | 1.2 | 3.5 | 6 | 1.2 | 6 | |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $t_r = t_f \leq$ 2.5 ns, duty cycle = 50%.
 D. When measuring propagation delay times of 3-state outputs, switch S1 is open.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN74F2373DBLE | OBSOLETE | SSOP | DB | 20 | | TBD | Call TI | Call TI |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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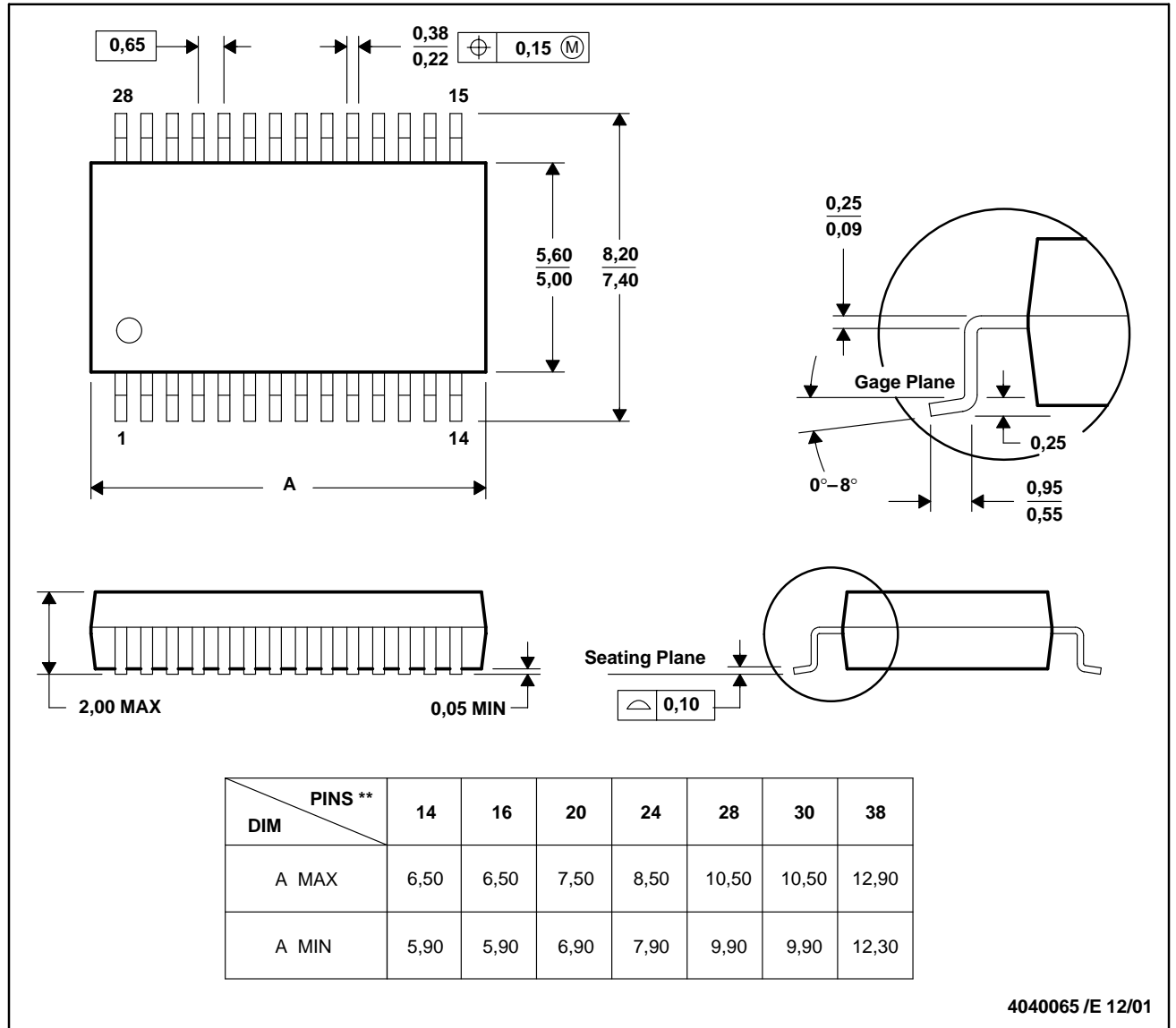
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MSS0002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G)**

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



4040065 / E 12/01

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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